

For use with TO -218/TO -247 packages

- 533101B02551G

Change Product

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Products

Quick Reference

Check distributor

part inventory

Search by part #

Browse Products

-By Device
-By Product Line-Attachment Methods

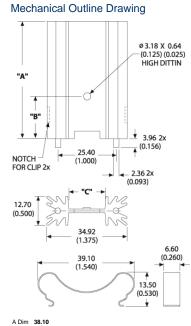
-Interface Materials
-Accessories -

Useful Links

Building a Part #
 Catalog Request
 Directions
 Find Distributor
 Find Sales Rep
 How to Order?

MSDS Safety Sheets
 Part # Cross Ref
 Quote Request
 RoHS Initiative

Sample Request

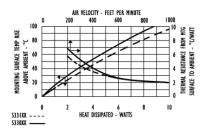


B Dim 21.59 C Dim 17.02

Part Number

RoHS √ Compliant

Thermal Curves





Thermal resistance value is based on a 75°C rise in natural convection

Product Information

Part #	Description	Finish	Board Mounting
533101B02551G	Extruded heat sink with radial fins and solderable pins and device clip	Black Anodize	N/A
soldering or reflow proce	mponent is functionally unaffecter esses used for semiconductor cirr resistance temperature is not app	cuits. The heat	

Not Exactly what you need?

We offer several options for those applications which require a more unique solution. For slight modifications of this part or other attachment options, finishes, and interface materials, contact your local representative . Challenge us with your thermal requirements - we can design custom solutions.